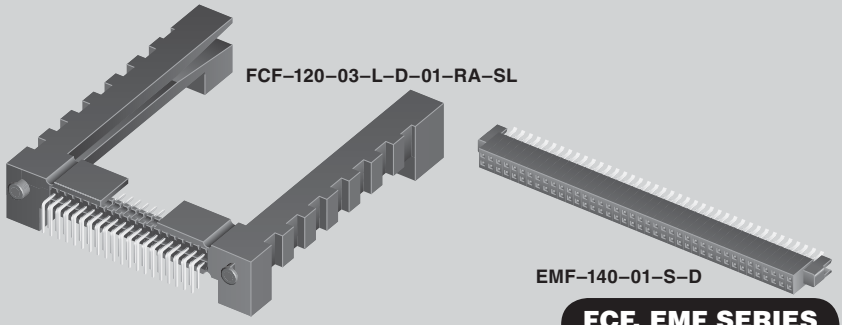
samtec



(1,27 mm) .050"

FCF, EMF SERIES

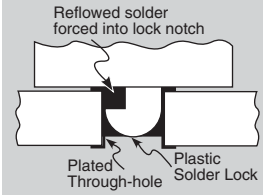
FLEXCARD™ TERMINAL & SOCKET STRIPS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?FCF or www.samtec.com?EMF

Insulator Material: Black Liquid Crystal Polymer
Terminal Material (FCF): Phosphor Bronze
Contact Material (EMF): BeCu
Plating: Sn or Au over 50µ" (1,27 µm) Ni
Operating Temp Range: FCF = -55°C to +105°C Tin FCF = -55°C to +125°C Gold EMF = -55°C to +125°C
Contact Resistance (EMF): 10 mΩ
Insertion Depth (EMF): (3,05 mm) .120" to (4,06 mm) .160"
Insertion Force (EMF): (Single contact only) 3.0 oz (0,83 N) avg.
Withdrawal Force (EMF): (Single contact only) 2.0 oz (0,56 N) avg.
Lead–Free Solderable: Yes
SMT Lead Coplanarity (EMF): (0,10 mm) .004" max (20) (0,15 mm) .006" max (30-50)
RoHS Compliant: Yes

APPLICATIONS



RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

TIGER EYE CONTACT™

Note: Some lengths, styles and options are non-standard, non-returnable.

FCF – 1 NO. PINS PER ROW – LEAD STYLE – PLATING OPTION – D – CARD SLOT – TAIL OPTION – SL

Mates with: EMF

20, 30, 40 & 50 (Standard sizes)

Specify LEAD STYLE from chart

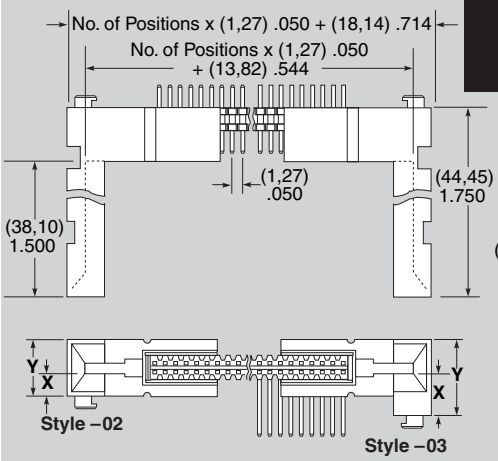
–L = 10µ" (0,25 µm) Gold on post, Matte Tin on tail

–S = 30µ" (0,76 µm) Gold on post, Matte Tin on tail

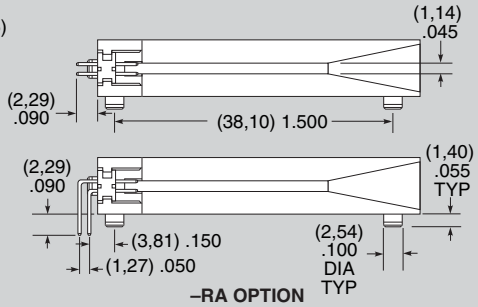
–01 = Accepts (0,80 mm) .031" thick card

–RA = Right Angle

(Leave blank for vertical version. Style –02 only)



LEAD STYLE	Y	CARD-TO-BOARD SPACE (X)
–02	(6,35) .250	(2,60) .1025
–03	(9,53) .375	(9,53) .375



EMF – 1 NO. PINS PER ROW – CARD THICKNESS – PLATING OPTION – D

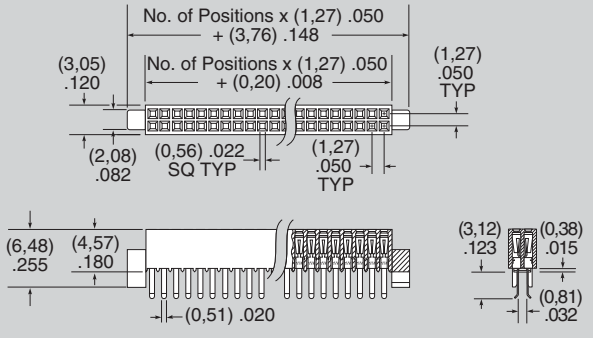
Mates with: FCF

20, 30, 40 & 50 (Standard sizes)

–01 = (0,80 mm) .031" thick board

–L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

–S = 30µ" (0,76 µm) Gold on contact, Matte Tin on tail



Due to technical progress, all designs, specifications and components are subject to change without notice.